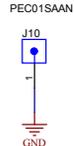
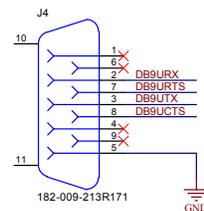


NOTE Only one of J3 or J4 must be installed



Orderable: EVM_orderable	Designed for: Public Release	Mod. Date: 20-Feb-15
TID #: N/A	Project Title: SZE Daughter Board	
Number: [blank]	Rev: 1.0	Sheet Title: [blank]
License: Version control disabled	Assembly Variant: [No Variations]	Sheet: 1 of 1
Drawn By: [blank]	File: TID_SerialBoosterPack_SchDoc	Size: B
Engineer: Samandan Reddy	Contact: http://www.ti.com/support	http://www.ti.com

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